

LNJ253W82RA

High Bright Surface Mounting Chip LED

SV (Side View) -0.5 Type

Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	4	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Lighting Color

- Red

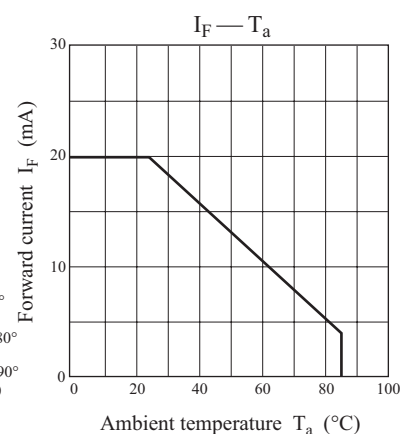
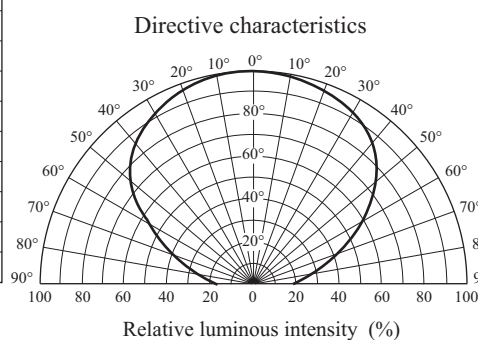
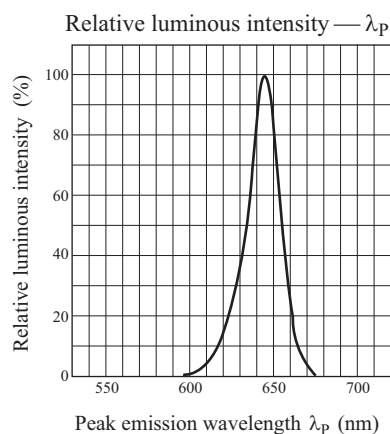
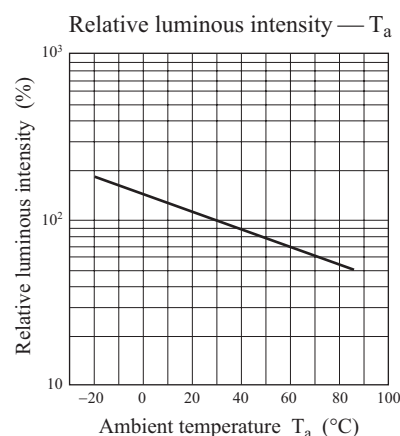
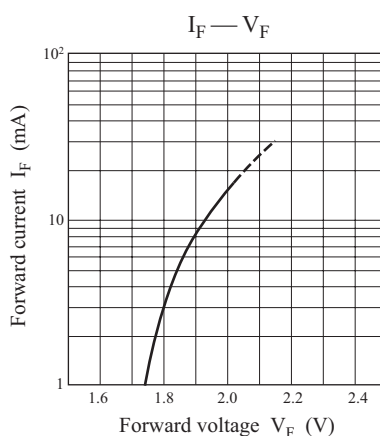
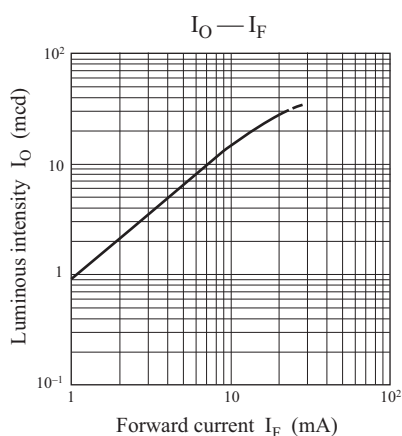
Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

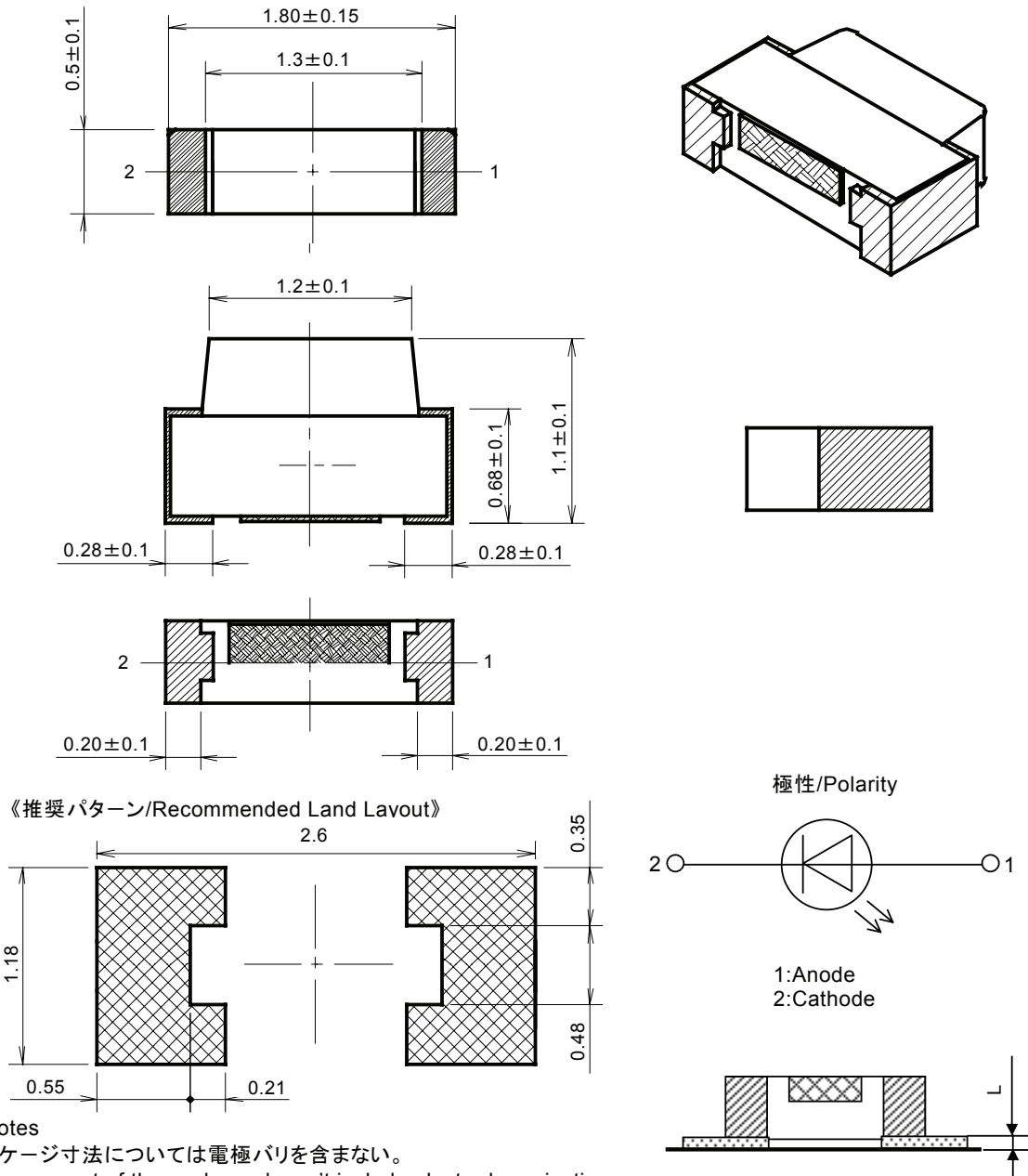
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	I_O	$I_F = 10 \text{ mA}$	8.0	15.0	60.8	mcd
Reverse current	I_R	$V_R = 4 \text{ V}$			100	μA
Forward voltage	V_F	$I_F = 10 \text{ mA}$		1.92	2.5	V
Peak emission wavelength	λ_p	$I_F = 10 \text{ mA}$		645		nm
Dominant emission wavelength *2	λ_d	$I_F = 10 \text{ mA}$	620	630	640	nm
Spectral half band width	$\Delta\lambda$	$I_F = 10 \text{ mA}$		22		nm

Note) *1: Measurement tolerance: $\pm 20\%$

*2: Measurement tolerance: $\pm 3 \text{ nm}$



■ Package (Unit: mm)



注記/Notes

1. パッケージ寸法については電極バリを含まない。
Measurement of the package doesn't include electrode projection.
2. 当製品は工法上、はんだ付け面端子端部にメッキバリカエリが発生することや、製品背面部に端子を有する縦型面実装タイプである為、リフローはんだ付けの際に不濡れ等が懸念されます。従いまして、はんだの種類のご検討ならびに各ロットに対し、適正なはんだ量を考慮してください。
Precaution to soldering
Assembly conditions such like mechanical lode in placing LED and also suitable volume and type of solder paste has to be fully investigated.
Insufficient soldering may occur because of the condition of solder terminal surface which is caused is caused by its unique production process.
3. 基本的に LED 直下範囲には固着フットパターン厚み(L)以上のシルク印刷をしないでください。
Please do not print silk more than fixture foot pattern thickness (L) basically within the range right under the LED.

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